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Material Change Summary for PCN14_0254

NOV 2014



Everywhere

Material Change Summary Table

Generic	Bump Composition on Die (At Amkor Taiwan)	Underfill Material	Solder Mask Material	Solder On Pad Composition
AD9737A AD9739A AD9739	Sn63Pb37 to Sn98.2Ag1.8	Namics U8439-1 to Namics U8410-73C	No Change	Sn63Pb37 to 96.5Sn3.0Ag0.5Cu
AD9148				
AD9119 AD9129				
AD9652				
AD9789				
AD9734 AD9735 AD9736		Shinetsu 75LV to Namics U8410-73C	AUS303 to AUS410	No SOP to 96.5Sn3.0Ag0.5Cu

Qualification Plan Summary of Bumping Process at Amkor Taiwan (AT5) and Flip Chip CSP_BGA at SCK3

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 32	February 2015
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A118</i>	3 x 32	February 2015
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	February 2015
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	February 2015

*Preconditioned per JEDEC/IPC J-STD-020